

ZXMP3A13F

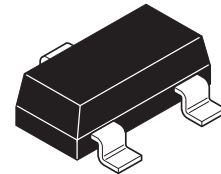
30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = -30V$; $R_{DS(ON)} = 0.21\Omega$; $I_D = -1.6A$

DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



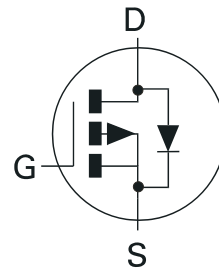
SOT23

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- SOT23 package

APPLICATIONS

- DC - DC converters
- Power management functions
- Disconnect switches
- Motor control



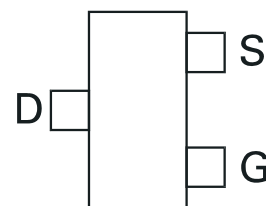
ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMP3A13FTA	7"	8mm	3000 units
ZXMP3A13FTC	13"	8mm	10000 units

DEVICE MARKING

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PINOUT



Top View

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ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	-30	V
Gate Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $V_{GS}=10V$; $T_A=25^\circ C$ (b) $V_{GS}=10V$; $T_A=70^\circ C$ (b) $V_{GS}=10V$; $T_A=25^\circ C$ (a)	I_D	-1.6 -1.3 -1.4	A
Pulsed Drain Current (c)	I_{DM}	-6	A
Continuous Source Current (Body Diode) (b)	I_S	-1.2	A
Pulsed Source Current (Body Diode) (c)	I_{SM}	-6	A
Power Dissipation at $T_A=25^\circ C$ (a) Linear Derating Factor	P_D	625 5	mW mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (b) Linear Derating Factor	P_D	806 6.4	mW mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to ambient (a)	$R_{\theta JA}$	200	$^\circ C/W$
Junction to ambient (b)	$R_{\theta JA}$	155	$^\circ C/W$

NOTES

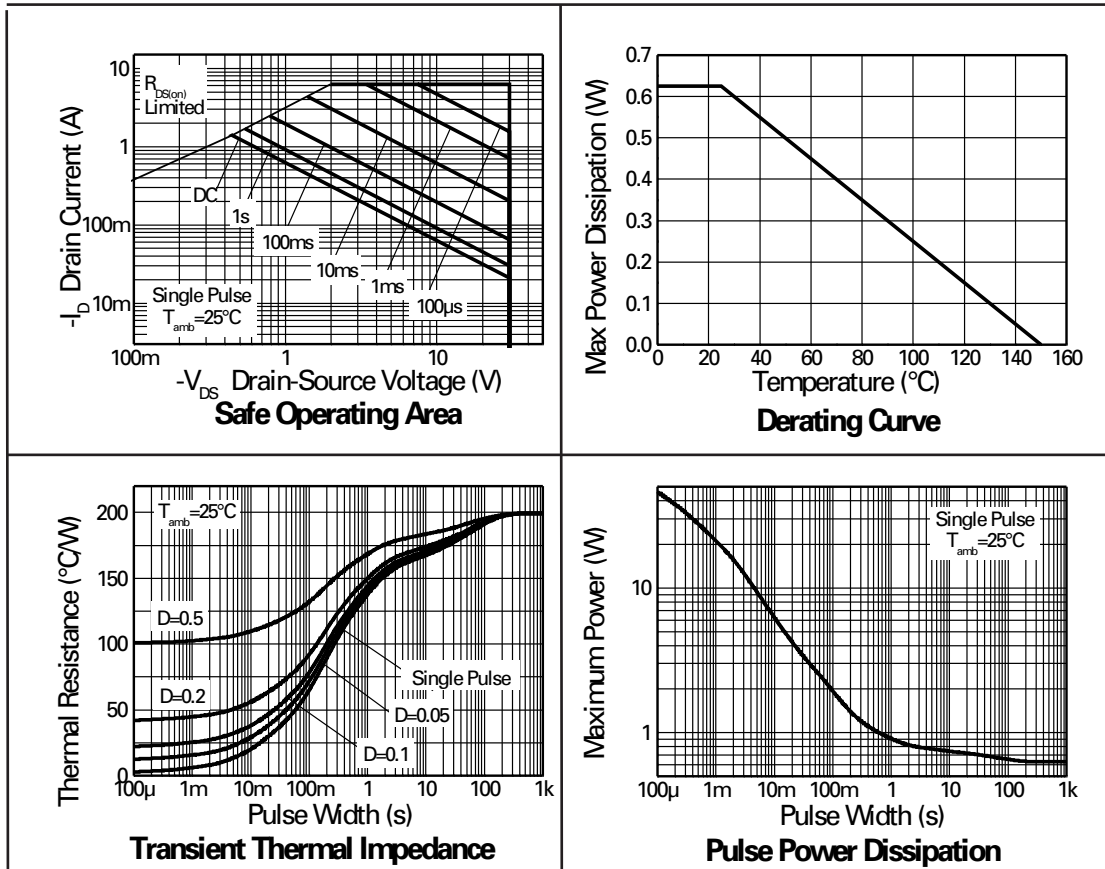
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at $t \leq 5$ secs.

(c) Repetitive rating 25mm x 25mm FR4 PCB, $D = 0.05$, pulse width 10 μs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

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CHARACTERISTICS



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ELECTRICAL CHARACTERISTICS (at $T_A = 25^\circ\text{C}$ unless otherwise stated)

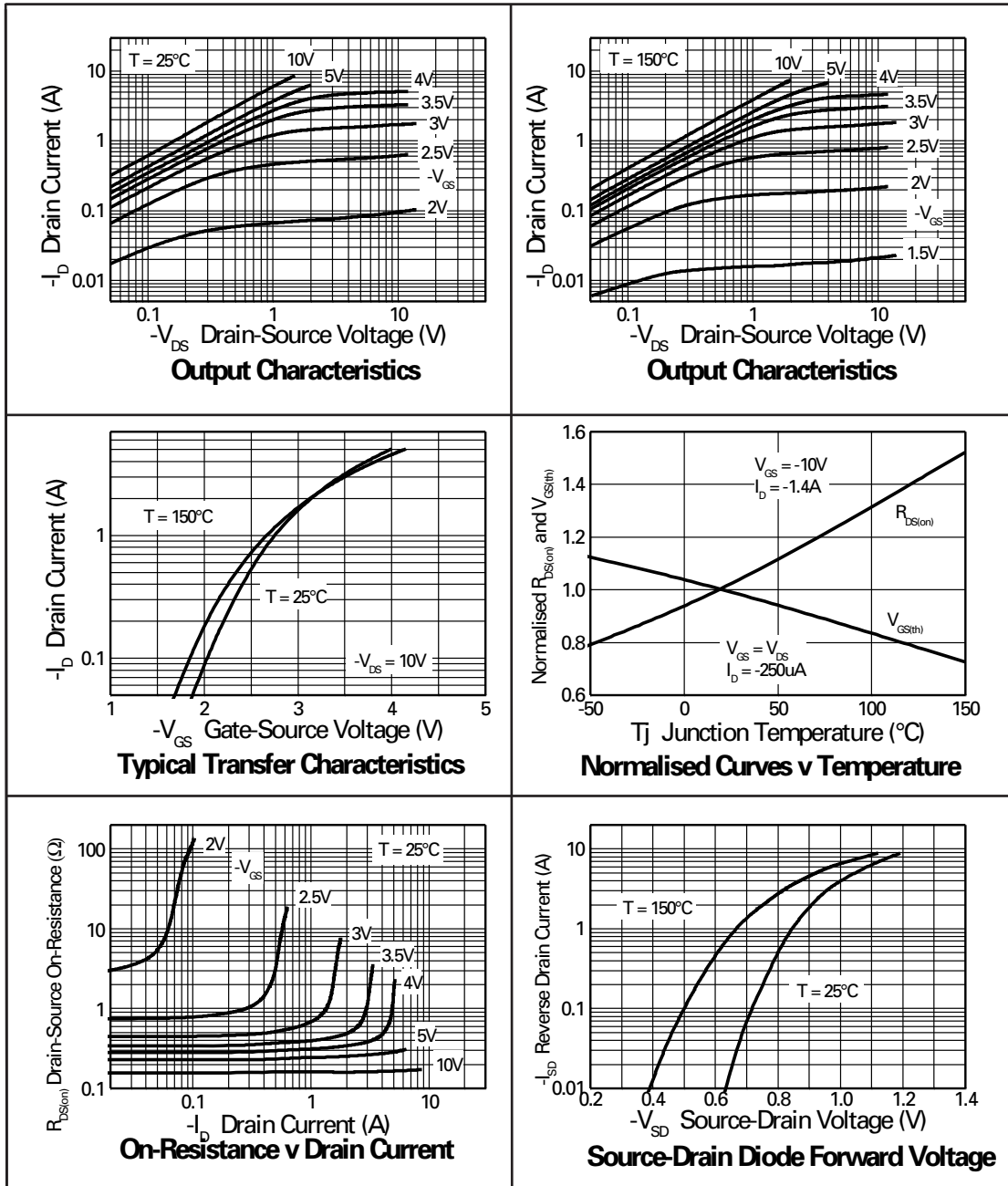
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-30			V	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}			-0.5	μA	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage	I_{GSS}			100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	-1.0			V	$I_D = -250\mu\text{A}, V_{DS} = V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.210 0.330	Ω Ω	$V_{GS} = -10\text{V}, I_D = -1.4\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -1.1\text{A}$
Forward Transconductance (1)(3)	g_{fs}		2.4		S	$V_{DS} = -15\text{V}, I_D = -1.4\text{A}$
DYNAMIC (3)						
Input Capacitance	C_{iss}		206		pF	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}		59.3		pF	
Reverse Transfer Capacitance	C_{rss}		49.2		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		1.5		ns	$V_{DD} = -15\text{V}, I_D = -1\text{A}$ $R_G = 6.0\Omega, V_{GS} = -10\text{V}$
Rise Time	t_r		3.0		ns	
Turn-Off Delay Time	$t_{d(off)}$		11.1		ns	
Fall Time	t_f		7.6		ns	
Gate Charge	Q_g		3.8		nC	$V_{DS} = -15\text{V}, V_{GS} = -5\text{V},$ $I_D = -1.4\text{A}$
Total Gate Charge	Q_g		6.4		nC	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V},$ $I_D = -1.4\text{A}$
Gate-Source Charge	Q_{gs}		0.69		nC	
Gate-Drain Charge	Q_{gd}		2.0		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		-0.85	-0.95	V	$T_J = 25^\circ\text{C}, I_S = -1.1\text{A},$ $V_{GS} = 0\text{V}$
Reverse Recovery Time (3)	t_{rr}		15.6		ns	$T_J = 25^\circ\text{C}, I_F = -0.95\text{A},$ $di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge (3)	Q_{rr}		9.6		nC	

NOTES:

- (1) Measured under pulsed conditions. Width=300 μs . Duty cycle $\leq 2\%$.
- (2) Switching characteristics are independent of operating junction temperature.
- (3) For design aid only, not subject to production testing.

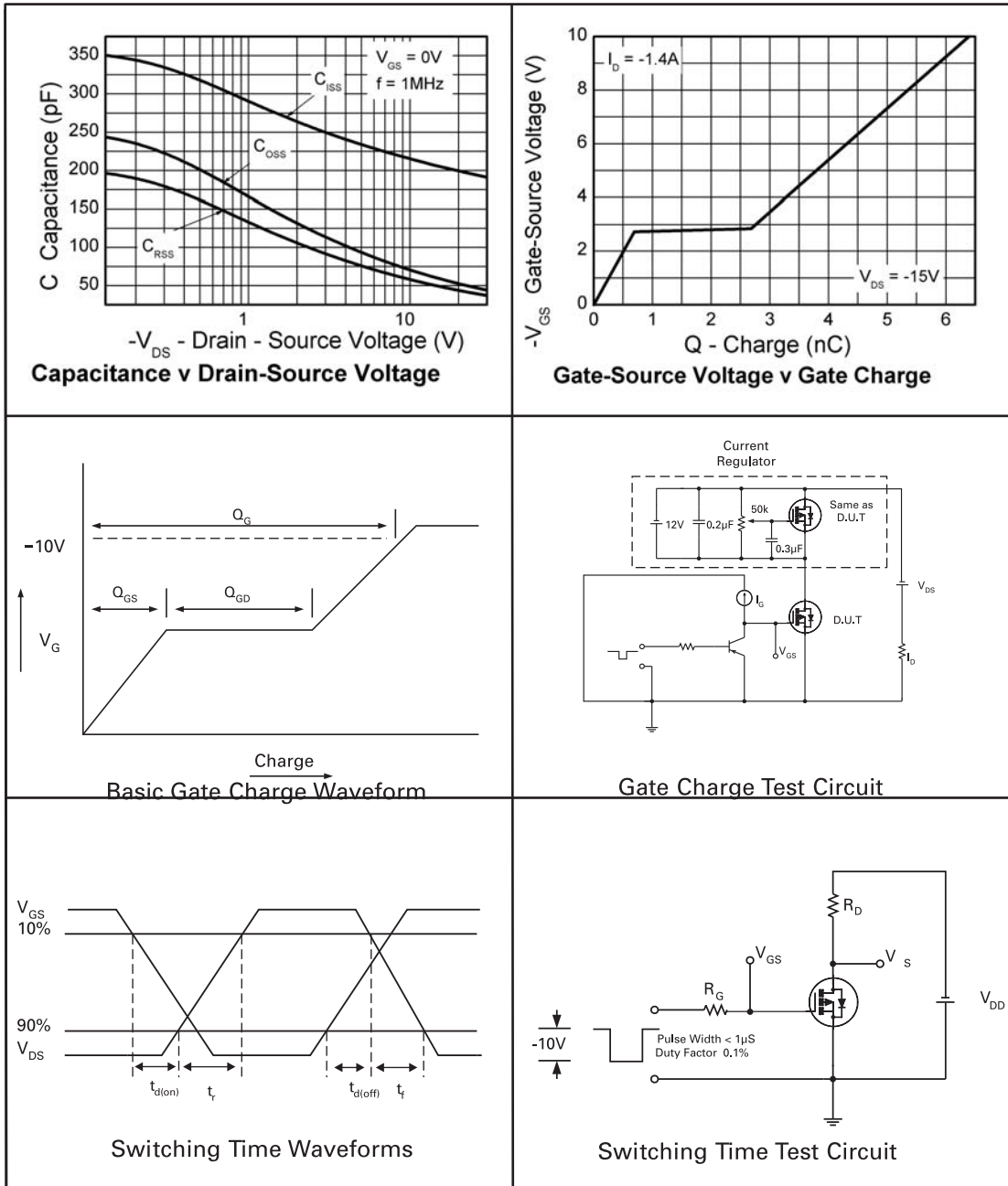
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



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"Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect

"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

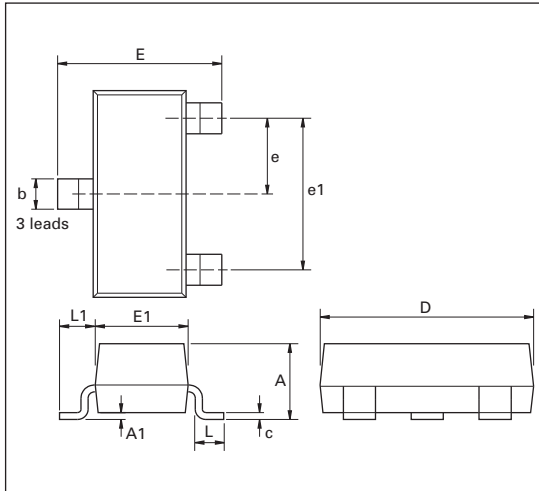
"Draft version" This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.

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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	-	1.12	-	0.044	e1	1.90 NOM		0.075 NOM	
A1	0.01	0.10	0.0004	0.004	E	2.10	2.64	0.083	0.104
b	0.30	0.50	0.012	0.020	E1	1.20	1.40	0.047	0.055
C	0.085	0.020	0.003	0.008	L	0.25	0.60	0.0098	0.0236
D	2.80	3.04	0.110	0.120	L1	0.45	0.62	0.018	0.024
e	0.95 NOM		0.037 NOM		---	---	---	---	---

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Europe	Americas	Asia Pacific	Corporate Headquarters
Zetex GmbH Kustermann-Park Balanstraße 59 D-81541 München Germany Telephone: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Zetex Inc 700 Veterans Memorial Hwy Hauppauge, NY 11788 USA Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com	Zetex (Asia) Ltd 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com	Zetex Semiconductors plc Zetex Technology Park Chadderton, Oldham, OL9 9LL United Kingdom Telephone (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com



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